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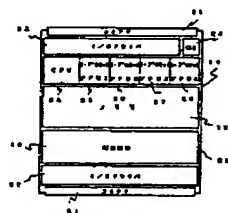
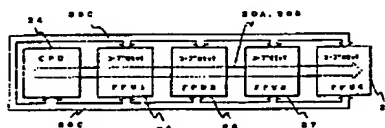
(54) **SEMICONDUCTOR DEVICE AND ELECTRONIC
EQUIPMENT PACKAGING SAID
SEMICONDUCTOR DEVICE**

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(57) Abstract:

PURPOSE: To improve the working speed of a system by extending the clock signal wiring connected to each clock signal external terminal of the 1st and 2nd semiconductor devices or a coprocessor signal wiring connected to a coprocessor signal external terminal on a packaging substrate in a substantial straight line.

CONSTITUTION: A clock signal wiring 20B connected to each clock signal external terminal of the 1st and 2nd semiconductor devices provided between a microprocessor 24 and a coprocessor 25 or coprocessor 26 - 28 or a coprocessor signal line 20A connected to a coprocessor signal external terminal is extended on a packaging substrate 20D in a substantial straight line. Thus the length of the wiring 20B or 20A formed on the substrate 20D can be shortened and therefore the signal delay is reduced. Then the working speed of a system can be improved for an electronic equipment 20.



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